

CLAIMS

1. A thin film forming apparatus (100) including a substrate support (10) for mounting a substrate (P) on which a thin film is to be formed, and a chamber (30) which encloses the substrate support (10) and has proper operation conditions, comprising:
5 adsorption means (S) attached to surfaces of components within the thin film forming apparatus except the substrate (P).
2. The apparatus as claimed in claim 1, wherein each of the adsorption means (S) is
10 constructed by applying a solder metal material (I) on a surface of a metal base material (B).
3. The apparatus as claimed in claim 1, wherein each of the adsorption means (S) is
15 constructed by applying a solder metal material (I) on a surface of a synthetic resin base material (B).
4. The apparatus as claimed in claim 2 or 3, wherein a plurality of grooves are formed on the surface of the base material (B).
- 20 5. The apparatus as claimed in claim 2 or 3, wherein a plurality of protrusions are formed on the surface of the base material (B).
6. The apparatus as claimed in claim 2 or 3, wherein the base material (B) is in the form of a net.